Dual Series Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage -0.35 V (Typ) @ $I_F = 10 \text{ mAdc}$
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS ($T_J = 125^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit	
Reverse Voltage	V_R	30	V	
Forward Power Dissipation @ T _A = 25°C Derate above 25°C	P _F	240 1.9	mW mW/°C	
Forward Current (DC)	IF	200 Max	mA	
Non–Repetitive Peak Forward Current, t _p < 10 msec	I _{FSM}	600	mA	
Repetitive Peak Forward Current Pulse Wave = 1 sec, Duty Cycle = 66%	I _{FRM}	300	mA	
Junction Temperature	T_J	-55 to 125	°C	
Storage Temperature Range	T _{stg}	-55 to +150	°C	
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	525	°C/W	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 board with minimum mounting pad.



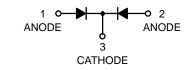
ON Semiconductor®

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30 VOLT DUAL COMMON CATHODE SCHOTTKY BARRIER DIODES



SC-89 CASE 463C STYLE 3



MARKING DIAGRAM



5C = Device Code M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

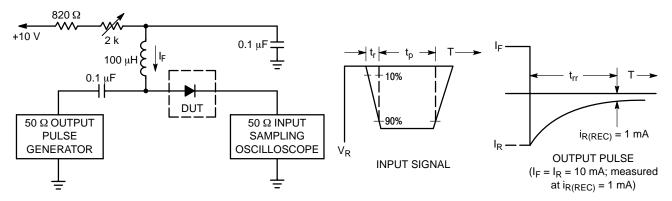
Device	Package	Shipping [†]
BAT54CXV3T1G	SC-89 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (EACH DIODE)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μA)	V _{(BR)R}	30	-	-	V
Total Capacitance (V _R = 1.0 V, f = 1.0 MHz)	C _T	_	7.6	10	pF
Reverse Leakage (V _R = 25 V)	I _R	-	0.5	2.0	μAdc
Forward Voltage (I _F = 0.1 mA) (I _F = 1.0 mA) (I _F = 10 mA) (I _F = 30 mA) (I _F = 100 mA)	V _F	- - - -	0.22 0.29 0.35 0.41 0.52	0.24 0.32 0.40 0.50 0.80	V
Reverse Recovery Time $(I_F = I_R = 10 \text{ mAdc}, I_{R(REC)} = 1.0 \text{ mAdc}, Figure 1)$	t _{rr}	_	-	5.0	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



Notes: 1. A 2.0 $k\Omega$ variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
- 3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

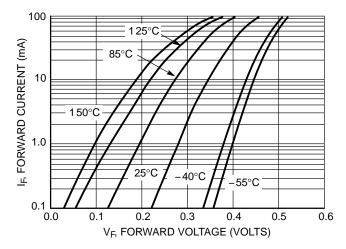


Figure 2. Forward Voltage

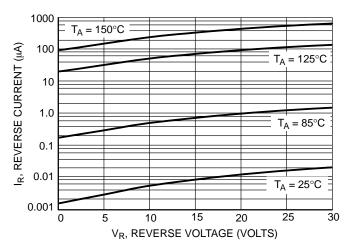


Figure 3. Leakage Current

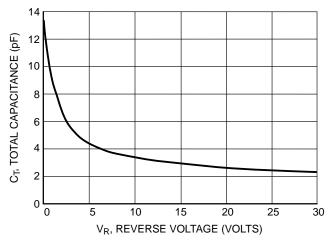
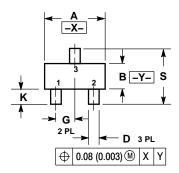
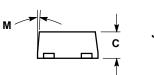


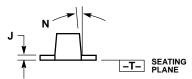
Figure 4. Total Capacitance

PACKAGE DIMENSIONS

SC-89, 3-LEAD CASE 463C-03 **ISSUE C**







NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- 463C-01 OBSOLETE, NEW STANDARD 463C-02.

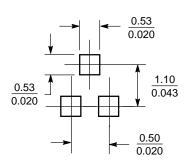
		MILLIMETERS				INCHES		
DII	и м	IN	NOM	MAX	MIN	NOM	MAX	
Α	1.5	50	1.60	1.70	0.059	0.063	0.067	
В	0.	75	0.85	0.95	0.030	0.034	0.040	
С	0.	60	0.70	0.80	0.024	0.028	0.031	
D	0.:	23	0.28	0.33	0.009	0.011	0.013	
G		0.50 BSC			0.020 BSC			
Н		0.53 REF			0	0.021 REF		
J	0.	10	0.15	0.20	0.004	0.006	0.008	
K	0.3	30	0.40	0.50	0.012	0.016	0.020	
L		1.10 REF			0.043 REF			
M	_			10			10	
N	_			10 _			10	
S	1.5	50	1.60	1.70	0.059	0.063	0.067	

STYLE 3:

- PIN 1. ANODE 2. ANODE

 - CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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